LN221RPH

Round Type

φ2.6 mm

Absolute Maximum Ratings $T_a = 25^{\circ}C$

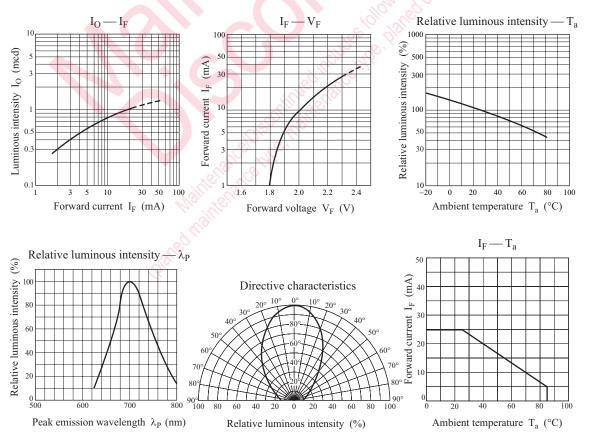
| Parameter | Symbol | Rating | Unit | |
|-------------------------------|------------------|-------------|------|--|
| Power dissipation | P _D | 70 | mW | |
| Forward current | I _F | 25 | mA | |
| Pulse forward current * | I _{FP} | 150 | mA | |
| Reverse voltage | V _R | 4 | V | |
| Operating ambient temperature | T _{opr} | -25 to +85 | °C | |
| Storage temperature | T _{stg} | -30 to +100 | °C | |

Lighting Color

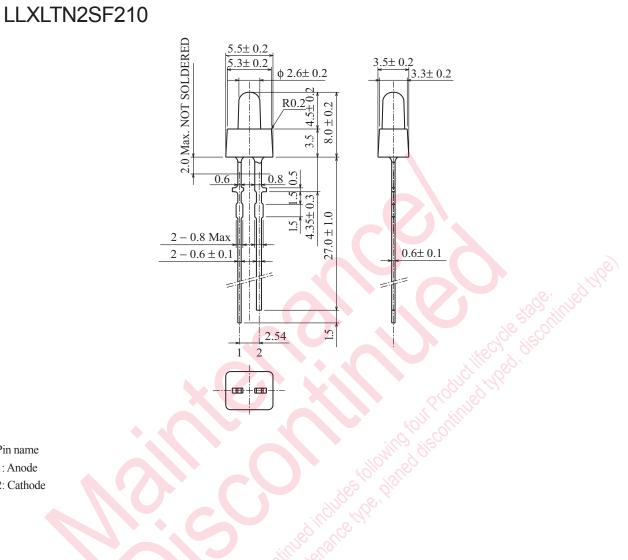
• Red

Electro-Optical Characteristics $T_a = 25^{\circ}C$

| Storage temperature | 1 stg | -30 10 + 100 | | | | | |
|---|----------------|-----------------------|------------|----------|---------|--------|---------|
| Note) *: The condition of I_{FP} is duty 10%, Pulse v | vidth 1 msec. | | | | | | |
| Electro-Optical Characteristics $T_a = 25^{\circ}C$ | | | | | × | Uni Os | 25 S |
| Parameter | Symbol | | Conditions | Min | Тур | Max | Unit |
| Luminous intensity | Io | | | 0.5 | S 1.0 8 | 5 | mcd |
| Reverse current | I _R | $V_R = 4 V$ | | | 1000 | 5 | μΑ |
| Forward voltage | V _F | $I_F = 20 \text{ mA}$ | X// | 0,00,00 | 2.2 | 2.8 | V |
| Peak emission wavelength | λ_P | $I_F = 20 \text{ mA}$ | | A differ | 700 | | nm |
| Spectral half band width | Δλ | $I_F = 20 \text{ mA}$ | | 50° | 100 | | nm |



Package (Unit: mm)



• Pin name

1: Anode

2: Cathode

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